								R	EVISI	ONS										
LTR		DESCRIPTION				DA	ATE (YI	R-MO-D	(A)		APPF	OVE)							
A	Chan	ges	in a	accordance with NOR 5962-R142-95.					95-05-12			K. Cottongim								
В	outl view remo	orrected figure 1 to move side view of case utlines X and Z to the right side of the top iew for the correct orientation. Figure 1; emoved the min limit for the D dimension of .880 inches (73.15 mm) for case outline Z. edrew entire documentsld						ongi	n											
REV SHEET																				
SHEET																				
SHEET REV SHEET				DE.																
SHEET REV SHEET REV STATU				REV			B	В	В	В	В	В	В	В	В	B 10	B	B 12	B 12	├
SHEET REV SHEET REV STATO OF SHEETS				SHE			B 1	B 2	В 3	B 4	5	6 DEFE	7 NSE S	8 UPPL	9 Y CEI	10	11	12	13	├
SHEET REV SHEET REV STATE OF SHEETS PMIC N/A STA	NDAF	CUIT		PREI Steve	EET	ncan BY	-			- -	5	6 DEFE	7 NSE S	8 UPPL	9	10	11	12	13	!
SHEET REV SHEET REV STATO OF SHEETS PMIC N/A STA MICRO DR. THIS DRAW FOR	NDAF OCIRO AWIN	CUIT G /AILAB		PREI Steve	PAREC PAREC	BY nes	1			4 MIC	5 ROC	6 DEFE	7 NSE S	8 SUPPL MBUS	9 Y CEI , OHIO	10 NTER 2 432	11 COLU	12 IMBUS	13	
SHEET REV SHEET REV STATO OF SHEETS PMIC N/A STA MICRO DR. THIS DRAW FOR 1 DEPA	NDAF OCIRC AWIN ING IS AV USE BY A ARTMENTI ENCIES O	CUIT G /AILAB ALL TS DF THE	ILE	SHE PREI Steve CHEC Micha	PAREC L. Du CKED ael Jor ROVEC dall A. (BY nes DBY Cottong	1 im	2		4 MIC	5 ROC	IRCU	7 NSE S	8 SUPPL MBUS YBRIG	9 Y CEI , OHIO	10 NTER 2 432 NEAR,	11 COLU 16-500	12 IMBUS	13	1

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DISTRIBUTION STATEMENT A. Approved for public release; distribution is unlimited.

5962-E419-98

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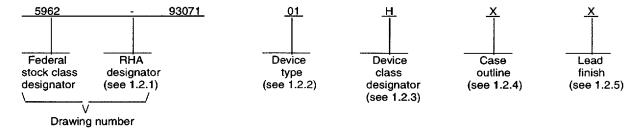
SHEET

OF

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1. SCOPE

- 1.1 <u>Scope</u>. This drawing documents five product assurance classes, class D (lowest reliability), class E, (exceptions), class G (lowest high reliability), class H (high reliability), and class K, (highest reliability) and a choice of case outlines and lead finishes are available and are reflected in the Part or Identifying Number (PIN). When available, a choice of radiation hardness assurance levels are reflected in the PIN.
 - 1.2 PIN. The PIN shall be as shown in the following example:



- 1.2.1 <u>Radiation hardness assurance (RHA) designator</u>. Device classes H and K RHA marked devices shall meet the MIL-PRF-38534 specified RHA levels and shall be marked with the appropriate RHA designator. A dash (-) indicates a non-RHA device.
 - 1.2.2 <u>Device type(s)</u>. The device type(s) shall identify the circuit function as follows:

Device type	Generic number	Circuit function
01	MTR2812D/883,MTR2812DF/883	DC-DC converter, 30 W, ±12 V output

1.2.3 <u>Device class designator</u>. This device class designator shall be a single letter identifying the product assurance level as follows:

Device class

Device performance documentation

D, E, G, H, or K

Certification and qualification to MIL-PRF-38534

1.2.4 Case outline(s). The case outline(s) shall be as designated in MIL-STD-1835 and as follows:

Outline letter	Descriptive designator	<u>Terminals</u>	Package style
X	See figure 1	10	Dual-in-line
Υ	See figure 1	10	Flange mount

1.2.5 Lead finish. The lead finish shall be as specified in MIL-PRF-38534.

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DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216-5000		REVISION LEVEL B	SHEET 2

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1.3 Absolute maximum ratings. 1/			
Input voltage range Power dissipation (P _D) Output power Lead soldering temperature (10 seconds) Storage temperature range	12 W 30.975 W +300°C		
1.4 Recommended operating conditions.			
Input voltage range	+16 V dc to +4 55°C to +125°	0 V dc ℃	
2. APPLICABLE DOCUMENTS			
2.1 Government specification, standards, and handbook. The of this drawing to the extent specified herein. Unless otherwise issue of the Department of Defense Index of Specifications and solitation.	specified, the issu	ies of these documents are	those listed in the
SPECIFICATION			
DEPARTMENT OF DEFENSE			
MIL-PRF-38534 - Hybrid Microcircuits, General Specific	ation for.		
STANDARDS			
DEPARTMENT OF DEFENSE			
MIL-STD-883 - Test Methods and Procedures for Micro MIL-STD-973 - Configuration Management. MIL-STD-1835 - Microcircuit Case Outlines.	oelectronics.		
HANDBOOK			
DEPARTMENT OF DEFENSE			
MIL-HDBK-780 - Standard Microcircuit Drawings.			
(Unless otherwise indicated, copies of the specification, stand Document Order Desk, 700 Robbins Avenue, Building 4D, Phila	lards, and handbo delphia, PA 1911	ook are available from the S 1-5094.)	Standardization
2.2 Order of precedence. In the event of a conflict between to of this drawing takes precedence. Nothing in this document, ho specific exemption has been obtained.	he text of this dra wever, supersede	wing and the references cites applicable laws and regu	ed herein, the text llations unless a
1/ Stresses above the absolute maximum rating may cause per maximum levels may degrade performance and affect relial	ermanent darnage bility.	to the device. Extended o	peration at the
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3. REQUIREMENTS

- 3.1 Item requirements. The individual item performance requirements for device classes D, E, G, H, and K shall be in accordance with MIL-PRF-38534. Compliance with MIL-PRF-38534 may include the performance of all tests herein or as designated in the device manufacturer's Quality Management (QM) plan or as designated for the applicable device class. Therefore, the tests and inspections herein may not be performed for the applicable device class (see MIL-PRF-38534). Futhermore, the manufacturers may take exceptions or use alternate methods to the tests and inspections herein and not perform them. However, the performance requirements as defined in MIL-PRF-38534 shall be met for the applicable device class.
- 3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38534 and herein.
 - 3.2.1 Case outline(s). The case outline(s) shall be in accordance with 1.2.4 herein and figure 1.
 - 3.2.2 Terminal connections. The terminal connections shall be as specified on figure 2.
- 3.3 <u>Electrical performance characteristics</u>. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full specified operating temperature range.
- 3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are defined in table I.
- 3.5 <u>Marking of Device(s)</u>. Marking of device(s) shall be in accordance with MIL-PRF-38534. The device shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's vendor similar PIN may also be marked as listed in QML-38534.
- 3.6 <u>Data</u>. In addition to the general performance requirements of MIL-PRF-38534, the manufacturer of the device described herein shall maintain the electrical test data (variables format) from the initial quality conformance inspection group A lot sample, for each device type listed herein. Also, the data should include a summary of all parameters manually tested, and for those which, if any, are guaranteed. This data shall be maintained under document revision level control by the manufacturer and be made available to the preparing activity (DSCC-VA) upon request.
- 3.7 <u>Certificate of compliance</u>. A certificate of compliance shall be required from a manufacturer in order to supply to this drawing. The certificate of compliance (original copy) submitted to DSCC-VA shall affirm that the manufacturer's product meets the performance requirements of MIL-PRF-38534 and herein.
- 3.8 <u>Certificate of conformance</u>. A certificate of conformance as required in MIL-PRF-38534 shall be provided with each lot of microcircuits delivered to this drawing.

4. QUALITY ASSURANCE PROVISIONS

4.1 <u>Sampling and inspection</u>. Sampling and inspection procedures shall be in accordance with MIL-PRF-38534 or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein.

STANDARD MICROCIRCUIT DRAWING DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216-5000 SIZE **5962-93071**REVISION LEVEL SHEET **4**

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Test	Symbol	Conditions -55°C ≤ T _C ≤ +125°C	Group A subgroups	Device type	Limi	Unit	
		-55°C ≤ T _C ≤ +125°C V _{IN} = 28 V dc ±.5 V dc no external sync, C _L = 0 unless otherwise specified			Min	Max	
Output voltage	V _{OUT}	I _{OUT} = ±1.25 A dc, (main)	2, 3	01	+11.88	+12.12	V dc
		I _{OUT} = ±1.25 A dc, (dual)	1 2, 3		<u>-11.82</u> -11.58	-12.18	
Output current	оит	V _{IN} = 16 V dc, 28 V dc, and 40 V dc, sum of both outputs	1, 2, 3		0.0	2500	mA
Output ripple voltage	V _{RIP}	I _{OUT} = ±1.25 A, B.W. = 10 kHz to 2 MHz	2, 3			80	mV p-p
Line regulation	VR _{LINE}	V _{IN} = 16 V dc to 40 V dc, I _{OUT} = ±1.25 A, (main)	1, 2, 3			50	mV
		V _{IN} = 16 V dc to 40 V dc, I _{OUT} = ±1.25 A, (dual)				150	
Load regulation	VR _{LOAD}	I _{OUT} = 0 to ±1.25 A, (main)	1, 2, 3			50	mV
		$I_{OUT} = 0$ to ±1.25 A, (dual)				150	
Input current	I _{IN}	I _{OUT} = 0, inhibit (pin 2) = 0	1, 2, 3			8	mA
		l _{OUT} = 0, inhibit (pin 2)				75	
Input ripple current	I _{RIP}	I _{OUT} = ±1.25 A, B.W. = 10 kHz to 10 MHz	1, 2, 3	_		50	mA p-r
Efficiency	Eff	I _{OUT} = ±1.25 A	1	-	79		%
Isolation	ISO	Input to output or any pin to case (except pins 6, 7, and 8) at 500 V dc	2, 3	-	100		МΩ

See footnotes at end of table.

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Test	Symbol	Conditions -55°C ≤ T _C ≤ +125°C	Group A subgroups	Device type	Lim	nits	Unit					
		-55°C ≤ T _C ≤ +125°C V _{IN} = 28 V dc ±.5 V dc no external sync, C _L = 0 unless otherwise specified			Min	Max						
Power dissipation, load fault	PD	Short circuit	2, 3	01		10	_ w					
Switching frequency	Fs	I _{OUT} = ±1.25 A	4, 5, 6			5	550	650	kHz			
External sync range 3/	F _{SYNC}	I _{OUT} = ±1.25 A, TTL level to pin 9	4, 5, 6							500	675	kHz
Output response to step transient load changes 4/	V _{TLOAD}	50 percent load to/from 100 percent load Balanced loads	-				-300	+300	mV pk			
Recovery time, step transient load changes 2/4/5/	TT _{LOAD}	50 percent load to/from 100 percent load Balanced loads					200	μs				
Output response to transient step line changes 2/6/	V _{TLINE}	Input step from 16 V dc to 40 V dc, I _{OUT} = ±1.25 A			-400	+400	mV pk					
	:	Input step from 40 V dc to 16 V dc, I _{OUT} = ±1.25 A			-400	+400						
Recovery time, transient step line changes 2/5/	TTLINE	Input step from 16 V dc to 40 V dc, I _{OUT} = ±1.25 A	_			300	μs					
·		Input step from 40 V dc to 16 V dc, I _{OUT} = ±1.25 A				300						
Turn-on overshoot 2/	VtonOS	I _{OUT} = ±1.25 A				±120	mV pk					
Tum-on delay 7/	Ton _D	I _{OUT} = ±1.25 A						5	ms			
_oad fault recovery	Tr _{LF}	I _{OUT} = ±1.25 A				5						
See footnotes at end of table).			!								

MICROCIRCUIT DRAWING
DEFENSE SUPPLY CENTER COLUMBUS
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SIZE 5962-93071

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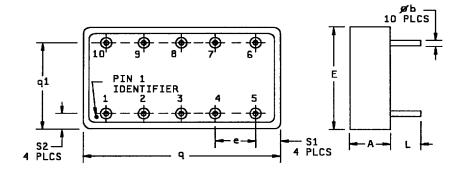
	TABLE I.	Electrical performance characte	eristics - Con	tinued.		-	
Test	Symbol	Conditions -55°C ≤ T _C ≤ +125°C	Group A subgroups	Device type	Lim	iits	Unit
		-55°C ≤ T _C ≤ +125°C V _{IN} = 28 V dc ±.5 V dc no external sync, C _L = 0 unless otherwise specified			Min	Max	
Capacitive load <u>1</u> / <u>2</u> /	CL	No effect on dc performance	4			500	μF

- $\underline{1}\!/$ Capacitive load may be any value from 0 to the maximum limit without compromising dc performance.
- 2/ Parameter shall be tested as part of design characterization and after design or process changes; therefore, the parameter shall be guaranteed to the limits specified in table I.
- 3/ A TTL level waveform (V_{IH} = 4.5 V minimum, V_{IL} = .8 V maximum) with a 50 percent ±10 percent duty cycle applied to sync input pin (pin 9) within the sync range frequency shall cause the converter's switching frequency to become synchronous with the frequency applied to the sync input pin (pin 9).
- 4/ Load step transition time 10 microseconds maximum.
- 5/ Recovery time is measured from the initiation of the transient to where V_{OUT} has returned to within ±1 percent of V_{OUT} final value.
- 6/ Input step transition time greater than 10 microseconds.
- If Turn-on delay time measurement is either for a step application of power at the input or the removal of a ground signal from the inhibit pin (pin 2) while power is applied to the input.

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Symbol	Millimeters		Inc	ches
	Min	Max	Min	Max
A		10.16		.400
фЬ	0.89	1.14	0.035	0.045
e	10.16	BSC	.400	BSC
E	28.07	28.32	1.105	1.115
L	6.09	6.60	0.240	0.260
q		53.21		2.095
q1	24.26	BSC	0.955 BSC	
S1	6.22	BSC	0.245 BSC	
S2	3.94	BSC	0.155 BSC	

NOTES:

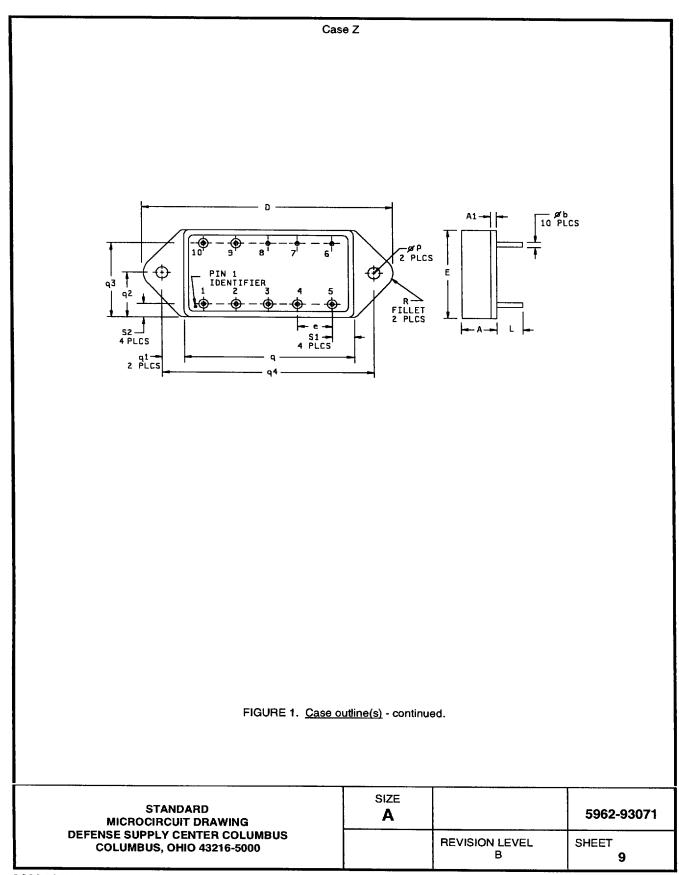
- 1. The case outline X was originally designed using the inch-pound units of measurement, in the event of conflict between the metric and inch-pound units, the inch-pound units shall take precedence.
- 2. Device weight: 52 grams maximum.

FIGURE 1. Case outline(s).

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Case Z - Continued

Symbol	Millimeters		Inc	ches
	Min	Max	Min	Max
Α		10.16		.400
A1	1.27	1.78	0.05	0.07
фЬ	0.89	1.14	0.035	0.045
D		73.66		2.900
e	10.16 BSC		.400	BSC
E	28.07	28.32	1.105	1.115
٦	6.09	6.60	0.240	0.260
фр	3.99	4.19	0.157	0.165
q	53.08 BSC		2.090 BSC	
q 1	5.84 BSC		0.230 BSC	
q2	14.10 BSC		0.55	5 BSC
q3	24.26 BSC		0.95	5 BSC
q4	64.52	65.02	2.54	2.56
R	4.19	4.44	0.165	0.175
S1	6.22 BSC		0.245 BSC	
S2	3.94 BSC		0.15	5 BSC

NOTES:

- 1. The case outline Z was originally designed using the inch-pound units of measurement, in the event of conflict between the metric and inch-pound units, the inch-pound units shall take precedence.
- 2. Unless otherwise specified, the tolerance is $\pm .01$ for two place decimals and $\pm .005$ for three place decimals.
- 3. Device weight: 55 grams maximum.

FIGURE 1. Case outline(s) - continued.

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Device type	01
Case outlines	X and Z
Terminal number	Terminal symbol
1	Positive input
2	Inhibit
3	Positive output
4	Output common
5	Negative output
6	Case ground
7	Case ground
8	Case ground
9	Sync input
10	Input common

FIGURE 2. <u>Terminal connections</u>.

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TABLE II. Electrical test requirements.

MIL-PRF-38534 test requirements	Subgroups (in accordance with MIL-PRF-38534, group A test table)
Interim electrical parameters	
Final electrical parameters	1*, 2, 3, 4, 5, 6
Group A test requirements	1, 2, 3, 4, 5, 6
Group C end-point electrical parameters	1
MIL-STD-883, group E end-point electrical parameters for RHA devices	Subgroups** (in accordance with method 5005, group A test table)

- * PDA applies to subgroup 1.
- ** When applicable to this standard microcircuit drawing, the subgroups shall be defined.
- 4.2 Screening. Screening shall be in accordance with MIL-PRF-38534. The following additional criteria shall apply:
 - a. Burn-in test, method 1015 of MIL-STD-883.
 - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to either DSCC-VA or the acquiring activity upon request. Also, the test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015 of MIL-STD-883.
 - (2) T_A as specified in accordance with table I of method 1015 of MIL-STD-883.
 - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.
- 4.3 <u>Conformance and periodic inspections</u>. Conformance inspection (CI) and periodic inspection (PI) shall be in accordance with MIL-PRF-38534 and as specified herein.
 - 4.3.1 Group A inspection (CI). Group A inspection shall be in accordance with MIL-PRF-38534 and as follows:
 - a. Tests shall be as specified in table II herein.
 - b. Subgroups 7, 8, 9, 10, and 11 shall be omitted.
 - 4.3.2 Group B inspection (PI). Group B inspection shall be in accordance with MIL-PRF-38534.

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- 4.3.3 Group C inspection (PI). Group C inspection shall be in accordance with MIL-PRF-38534 and as follows:
 - a. End-point electrical parameters shall be as specified in table II herein.
 - Steady-state life test, method 1005 of MIL-STD-883.
 - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to either DSCC-VA or the acquiring activity upon request. Also, the test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.
 - (2) TA as specified in accordance with table I of method 1005 of MIL-STD-883.
 - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.
- 4.3.4 Group D inspection (PI). Group D inspection shall be in accordance with MIL-PRF-38534.
- 4.3.5 <u>Group E inspection</u>. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein). RHA levels shall be M, D, R, and H. RHA quality conformance inspection sample tests shall be performed at the RHA level specified in the acquisition document.
 - a. RHA tests for levels M, D, R, and H shall be performed through each level to determine at what levels the devices meet the RHA requirements. These RHA tests shall be performed for initial qualification and after design or process changes which may affect the RHA performance of the device.
 - b. End-point electrical parameters shall be as specified in table II herein.
 - c. Prior to total dose irradiation, each selected sample shall be assembled in its qualified package. It shall pass the specified group A electrical parameters in table I for subgroups specified in table II herein.
 - d. The devices shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38534 for RHA level being tested, and meet the postirradiation end-point electrical parameter limits as defined in table I at T_A = +25°C ±5 percent, after exposure.
 - e. Prior to and during total dose irradiation testing, the devices shall be biased to establish a worst case condition as specified in the radiation exposure circuit.
 - For device classes H and K, subgroups 1 and 2 in table V, method 5005 of MIL-STD-883 shall be tested as appropriate for device construction.
 - g. When specified in the purchase order or contract, a copy of the RHA delta limits shall be supplied.
 - 5. PACKAGING
 - 5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38534.
 - 6. NOTES
- 6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.
- 6.2 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-973 using DD Form 1692, Engineering Change Proposal.

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6.4 <u>Record of users</u> . Military and industrial users shall inform Defense Supply Center Columbus when a system application requires configuration control and the applicable SMD. DSCC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DSCC-VA, telephone (614) 692-0526.			
6.5 Comments. Comments on this drawing should be directed to DSCC-VA, Columbus, Ohio 43216-5000, or telephone (614) 692-0512.			
6.6 Sources of supply. Sources of supply are listed in QML-38534. The vendors listed in QML-38534 have submitted a certificate of compliance (see 3.7 herein) to DSCC-VA and have agreed to this drawing.			
		-	
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STANDARD MICROCIRCUIT DRAWING SOURCE APPROVAL BULLETIN

DATE: 98-07-01

Approved sources of supply for SMD 5962-93071 are listed below for immediate acquisition only and shall be added to QML-38534 during the next revision. QML-38534 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DSCC-VA. This bulletin is superseded by the next dated revision of QML-38534.

Standard	Vendor	Vendor
microcircuit drawing	CAGE	similar
PIN <u>1</u> /	number	PIN <u>2</u> /
5962-9307101HXA	50821	MTR2812D/883
5962-9307101HXC	50821	MTR2812D/883
5962-9307101HZA	50821	MTR2812DF/883
5962-9307101HZC	50821	MTR2812DF/883

- 1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.
- 2/ <u>Caution</u>. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE number

50821

Vendor name and address

Interpoint Corporation 10301 Willows Road Redmond, WA 98052

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in this information bulletin.

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